

Assembly

TYPES OF DIE ATTACH

- ✂ Vacuum Solder Reflow of Die to Heatspreader
 - ✂ 95% Lead / 5% Tin
 - ✂ 96% Tin / 4% Silver
 - ✂ 80% Gold / 20% Tin
- ✂ Conductive Epoxy Die attach
- ✂ Non Conductive Die attach
- ✂ Die on Die epoxy attach
- ✂ Flip Chip



Samsung Die placement



Ultron UH420